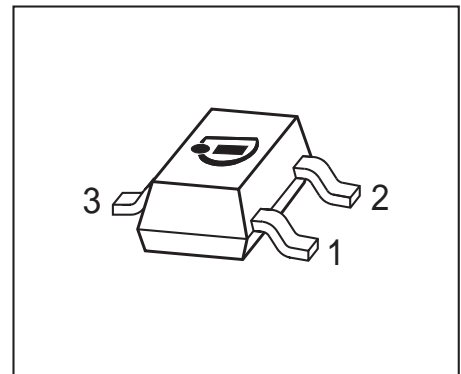


**NPN Silicon RF Transistor\***

- For low noise, high-gain amplifiers
- For linear broadband amplifiers
- Special application: antenna amplifiers
- Pb-free (RoHS compliant) package <sup>1)</sup>
- Qualified according AEC Q101



\* Short term description



**ESD (Electrostatic discharge) sensitive device, observe handling precaution!**

Type	Marking	Pin Configuration			Package
BFR106	R7s	1=B	2=E	3=C	SOT23

**Maximum Ratings**

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CEO}$	15	V
Collector-emitter voltage	$V_{CES}$	20	
Collector-base voltage	$V_{CBO}$	20	
Emitter-base voltage	$V_{EBO}$	3	
Collector current	$I_C$	210	mA
Base current	$I_B$	21	
Total power dissipation- $T_S \leq 73 \text{ }^\circ\text{C}$	$P_{tot}$	700	mW
Junction temperature	$T_j$	150	$^\circ\text{C}$
Ambient temperature	$T_A$	-65 ... 150	
Storage temperature	$T_{stg}$	-65 ... 150	

**Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>2)</sup>	$R_{thJS}$	$\leq 110$	K/W

<sup>1</sup>Pb-containing package may be available upon special request

<sup>2</sup>For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC Characteristics</b>					
Collector-emitter breakdown voltage $I_C = 1\text{ mA}, I_B = 0$	$V_{(BR)CEO}$	15	-	-	V
Collector-emitter cutoff current $V_{CE} = 20\text{ V}, V_{BE} = 0$	$I_{CES}$	-	-	10	$\mu\text{A}$
Collector-base cutoff current $V_{CB} = 10\text{ V}, I_E = 0$	$I_{CBO}$	-	-	100	nA
Emitter-base cutoff current $V_{EB} = 2\text{ V}, I_C = 0$	$I_{EBO}$	-	-	100	$\mu\text{A}$
DC current gain- $I_C = 70\text{ mA}, V_{CE} = 8\text{ V}, \text{ pulse measured}$	$h_{FE}$	70	100	140	-

**Electrical Characteristics at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

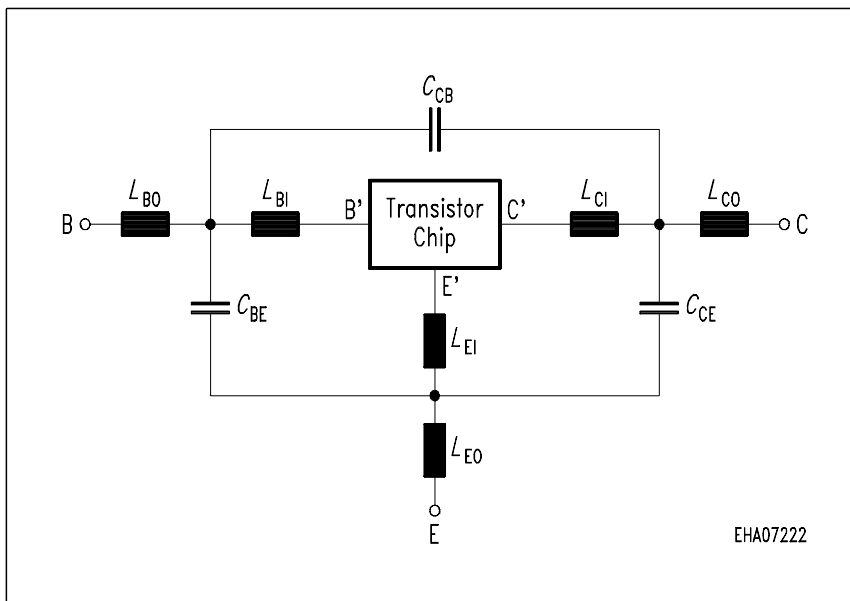
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>AC Characteristics (verified by random sampling)</b>					
Transition frequency $I_C = 70\text{ mA}$ , $V_{CE} = 8\text{ V}$ , $f = 500\text{ MHz}$	$f_T$	3.5	5	-	GHz
Collector-base capacitance $V_{CB} = 10\text{ V}$ , $f = 1\text{ MHz}$ , $V_{BE} = 0$ , emitter grounded	$C_{cb}$	-	0.85	1.2	pF
Collector emitter capacitance $V_{CE} = 10\text{ V}$ , $f = 1\text{ MHz}$ , $V_{BE} = 0$ , base grounded	$C_{ce}$	-	0.27	-	
Emitter-base capacitance $V_{EB} = 0.5\text{ V}$ , $f = 1\text{ MHz}$ , $V_{CB} = 0$ , collector grounded	$C_{eb}$	-	3.9	-	
Noise figure $I_C = 20\text{ mA}$ , $V_{CE} = 6\text{ V}$ , $Z_S = Z_{Sopt}$ , $f = 900\text{ MHz}$ $I_C = 20\text{ mA}$ , $V_{CE} = 6\text{ V}$ , $Z_S = Z_{Sopt}$ , $f = 1.8\text{ GHz}$	$F$	-	1.8	-	dB
		-	3	-	
Power gain, maximum available <sup>1)</sup> $I_C = 70\text{ mA}$ , $V_{CE} = 8\text{ V}$ , $Z_S = Z_{Sopt}$ , $Z_L = Z_{Lopt}$ , $f = 900\text{ MHz}$ $I_C = 70\text{ mA}$ , $V_{CE} = 8\text{ V}$ , $Z_S = Z_{Sopt}$ , $Z_L = Z_{Lopt}$ , $f = 1.8\text{ GHz}$	$G_{ma}$	-	13	-	
		-	8.5	-	
Transducer gain $I_C = 70\text{ mA}$ , $V_{CE} = 8\text{ V}$ , $Z_S = Z_L = 50\ \Omega$ , $f = 900\text{ MHz}$ $I_C = 70\text{ mA}$ , $V_{CE} = 8\text{ V}$ , $Z_S = Z_L = 50\ \Omega$ , $f = 1.8\text{ MHz}$	$ S_{21e} ^2$	-	10.5	-	dB
		-	5	-	

$$^1G_{ma} = |S_{21e} / S_{12e}| (k - (k^2 - 1)^{1/2})$$

**SPICE Parameter (Gummel-Poon Model, Berkley-SPICE 2G.6 Syntax):**
**Transistor Chip Data:**

IS =	1.8998	fA	BF =	132.75	-	NF =	0.89608	-
VAF =	15	V	IKF =	0.44125	A	ISE =	71.424	fA
NE =	1.3235	-	BR =	11.407	-	NR =	0.91008	-
VAR =	4.1613	V	IKR =	0.010016	A	ISC =	2.0992	fA
NC =	1.4602	-	RB =	1.2652	$\Omega$	IRB =	0.028135	mA
RBM =	1.0893	$\Omega$	RE =	1.1351	-	RC =	0.27485	$\Omega$
CJE =	5.0933	fF	VJE =	0.85909	V	MJE =	0.69062	-
TF =	35.78	ps	XTF =	0.44444	-	VTF =	0.10681	V
ITF =	62.059	mA	PTF =	0	deg	CJC =	2327.8	fF
VJC =	0.81533	V	MJC =	0.46849	-	XCJC =	0.14496	-
TR =	1.2466	ns	CJS =	0	fF	VJS =	0.75	V
MJS =	0	-	XTB =	0	-	EG =	1.11	eV
XTI =	3	-	FC =	0.92887	-	TNOM	300	K

All parameters are ready to use, no scaling is necessary. Extracted on behalf of Infineon Technologies AG by: Institut für Mobil- und Satellitentechnik (IMST)

**Package Equivalent Circuit:**


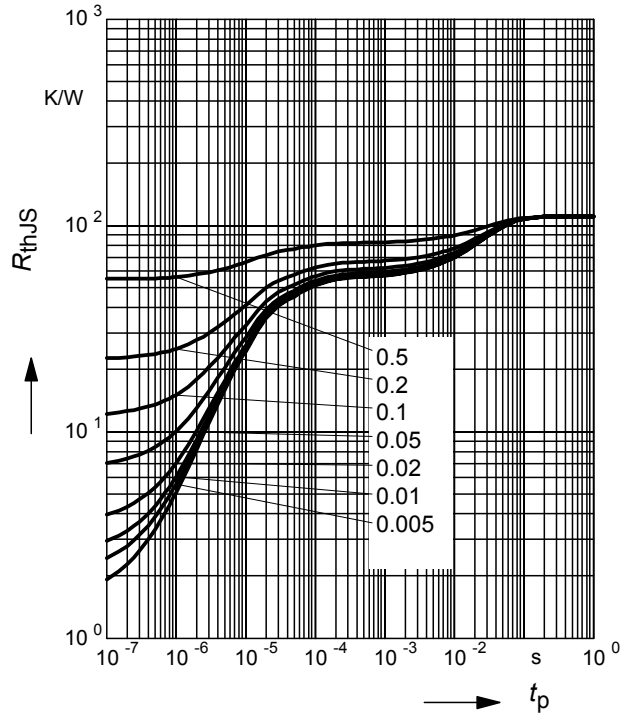
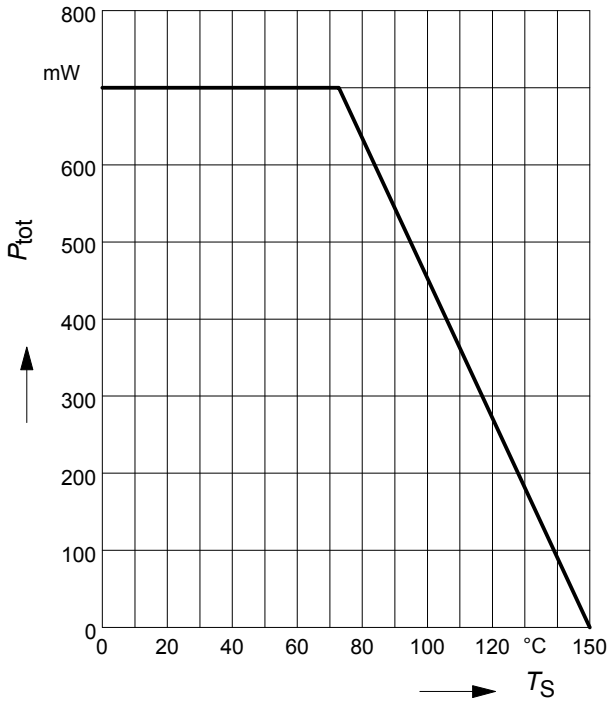
$L_{BI}$ =	0.85	nH
$L_{BO}$ =	0.51	nH
$L_{EI}$ =	0.69	nH
$L_{EO}$ =	0.61	nH
$L_{CI}$ =	0	nH
$L_{CO}$ =	0.43	nH
$C_{BE}$ =	73	fF
$C_{CB}$ =	84	fF
$C_{CE}$ =	165	fF

Valid up to 6GHz

For examples and ready to use parameters please contact your local Infineon Technologies distributor or sales office to obtain a Infineon Technologies CD-ROM or see Internet: <http://www.infineon.com>

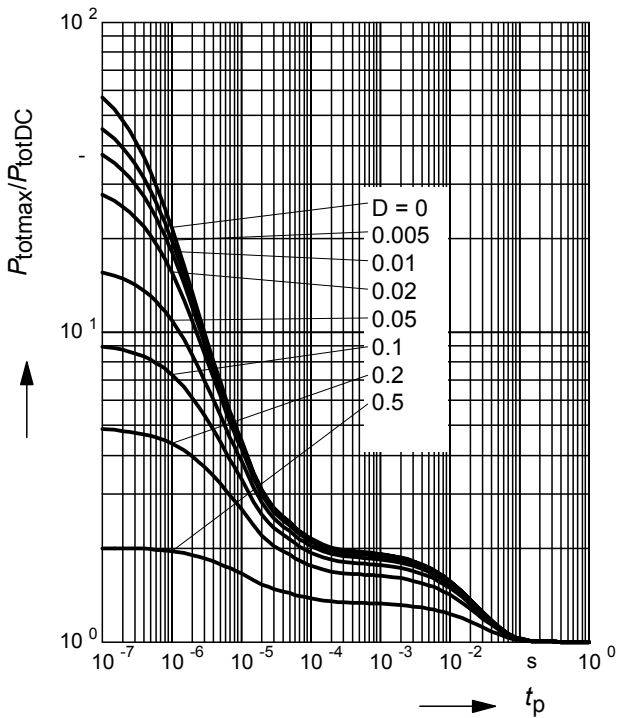
Total power dissipation  $P_{tot} = f(T_S)$

Permissible Pulse Load  $R_{thJS} = f(t_p)$

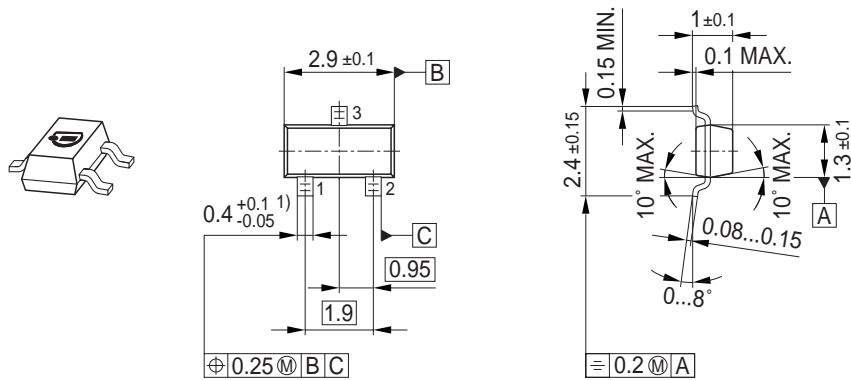


**Permissible Pulse Load**

$P_{totmax}/P_{totDC} = f(t_p)$

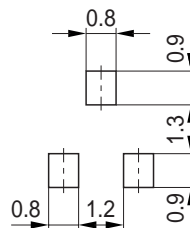


Package Outline

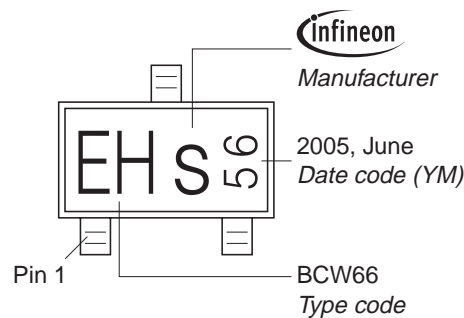


1) Lead width can be 0.6 max. in dambar area

Foot Print

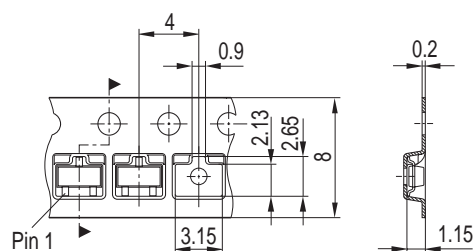


Marking Layout (Example)



Standard Packing

Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



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